

FDD6670AS

30V N-Channel PowerTrench® SyncFET™

General Description

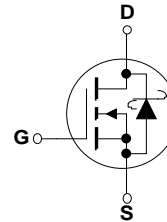
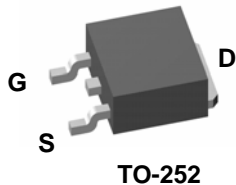
The FDD6670AS is designed to replace a single MOSFET and Schottky diode in synchronous DC:DC power supplies. This 30V MOSFET is designed to maximize power conversion efficiency, providing a low $R_{DS(ON)}$ and low gate charge. The FDD6670AS includes a patented combination of a MOSFET monolithically integrated with a schottky diode. The performance of the FDD6670AS as the low-side switch in a synchronous rectifier is indistinguishable from the performance of the FDD6670A in parallel with a Schottky diode.

Applications

- DC/DC converter
- Low side notebook

Features

- 76 A, 30 V $R_{DS(ON)}$ max= 8.0 m Ω @ $V_{GS} = 10$ V
 $R_{DS(ON)}$ max= 10.4 m Ω @ $V_{GS} = 4.5$ V
- Includes SyncFET Schottky body diode
- Low gate charge (29nC typical)
- High performance trench technology for extremely low $R_{DS(ON)}$
- High power and current handling capability



Absolute Maximum Ratings T_A=25°C unless otherwise noted

| Symbol | Parameter | Ratings | Units |
|-----------------------------------|--|-------------|-------|
| V _{DSS} | Drain-Source Voltage | 30 | V |
| V _{GSS} | Gate-Source Voltage | ±20 | V |
| I _D | Drain Current – Continuous (Note 3) | 76 | A |
| | – Pulsed (Note 1a) | 100 | |
| P _D | Power Dissipation (Note 1) | 70 | W |
| | | 3.2 | |
| | | 1.3 | |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | –55 to +150 | °C |

Thermal Characteristics

| | | | |
|------------------|---|-----|------|
| R _{θJC} | Thermal Resistance, Junction-to-Case (Note 1) | 1.8 | °C/W |
| R _{θJA} | Thermal Resistance, Junction-to-Ambient (Note 1a) | 40 | °C/W |
| R _{θJA} | Thermal Resistance, Junction-to-Ambient (Note 1b) | 96 | °C/W |

Package Marking and Ordering Information

| Device Marking | Device | Reel Size | Tape width | Quantity |
|----------------|-----------------------|-----------|------------|------------|
| FDD6670AS | FDD6670AS | 13" | 16mm | 2500 units |
| FDD6670AS | FDD6670AS_NL (Note 4) | 13" | 16mm | 2500 units |

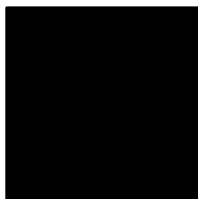
| Electrical Characteristics T_A = 25°C unless otherwise noted | | | | | | |
|---|--|---|-----|-------------------|---------------------|-------|
| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
| Drain-Source Avalanche Ratings (Note 2) | | | | | | |
| W _{DSS} | Drain-Source Avalanche Energy | Single Pulse, V _{DD} = 15 V, I _D =14A | | | 245 | mJ |
| I _{AR} | Drain-Source Avalanche Current | | | | 14 | A |
| Off Characteristics | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} = 0 V, I _D = 1 mA | 30 | | | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | I _D = 10 mA, Referenced to 25°C | | 29 | | mV/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 24 V, V _{GS} = 0 V | | | 500 | μA |
| | | V _{DS} = 24 V, V _{GS} = 0 V, T _J = 125°C | | 6.5 | | mA |
| I _{GSS} | Gate-Body Leakage | V _{GS} = ±20 V, V _{DS} = 0 V | | | ±100 | nA |
| On Characteristics (Note 2) | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = 1 mA | 1 | 1.8 | 3 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate Threshold Voltage Temperature Coefficient | I _D = 10 mA, Referenced to 25°C | | -3.3 | | mV/°C |
| R _{DS(on)} | Static Drain-Source On-Resistance | V _{GS} = 10 V, I _D = 13.8 A V _{GS} = 4.5 V, I _D = 11.7 A V _{GS} = 10 V, I _D = 13.8A, T _J = 125°C | | 6.8 8.3 9.3 | 8.0 10.4 11.6 | mΩ |
| I _{D(on)} | On-State Drain Current | V _{GS} = 10 V, V _{DS} = 5 V | 50 | | | A |
| g _{FS} | Forward Transconductance | V _{DS} = 15 V, I _D = 13.8 A | | 52 | | S |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} = 15 V, V _{GS} = 0 V, f = 1.0 MHz | | 1580 | | pF |
| C _{oss} | Output Capacitance | | | 440 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 170 | | pF |
| R _G | Gate Resistance | V _{GS} = 15 mV, f = 1.0 MHz | | 1.8 | | Ω |
| Switching Characteristics (Note 2) | | | | | | |
| t _{d(on)} | Turn-On Delay Time | V _{DS} = 15 V, I _D = 1 A, V _{GS} = 10 V, R _{GEN} = 6 Ω | | 10 | 20 | ns |
| t _r | Turn-On Rise Time | | | 12 | 22 | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 28 | 45 | ns |
| t _f | Turn-Off Fall Time | | | 20 | 36 | ns |
| t _{d(on)} | Turn-On Delay Time | V _{DS} = 15 V, I _D = 1 A, V _{GS} = 4.5 V, R _{GEN} = 6 Ω | | 15 | 27 | ns |
| t _r | Turn-On Rise Time | | | 16 | 29 | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 26 | 42 | ns |
| t _f | Turn-Off Fall Time | | | 13 | 23 | ns |
| Q _{g(TOT)} | Total Gate Charge at V _{GS} =10V | V _{DS} = 15 V, I _D = 13.8 A, | | 29 | 40 | nC |
| Q _{g(TOT)} | Total Gate Charge at V _{GS} =5V | | | 16 | 22 | nC |
| Q _{gs} | Gate-Source Charge | | | 4.6 | | nC |
| Q _{gd} | Gate-Drain Charge | | | 5.5 | | nC |
| Drain-Source Diode Characteristics | | | | | | |
| V _{SD} | Drain-Source Diode Forward Voltage | V _{GS} = 0 V, I _S = 3.5 A (Note 2) V _{GS} = 0 V, I _S = 7 A (Note 2) | | 0.46 0.59 | 0.7 | V |
| t _{rr} | Diode Reverse Recovery Time | I _F = 3.5 A, | | 20 | | ns |
| Q _{rr} | Diode Reverse Recovery Charge | d _I /d _t = 300 A/μs (Note 3) | | 15 | | nC |

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

Notes:

- $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) $R_{\theta JA} = 40^\circ\text{C/W}$ when mounted on a 1in^2 pad of 2 oz copper



b) $R_{\theta JA} = 96^\circ\text{C/W}$ when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

- Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%

- Maximum current is calculated as:
$$\sqrt{\frac{P_D}{R_{DS(ON)}}}$$

where P_D is maximum power dissipation at $T_C = 25^\circ\text{C}$ and $R_{DS(on)}$ is at $T_{J(max)}$ and $V_{GS} = 10\text{V}$. Package current limitation is 21A

- FDD6670AS_NL is a lead free product. The FDD6670AS_NL marking will appear on the reel label.

Typical Characteristics

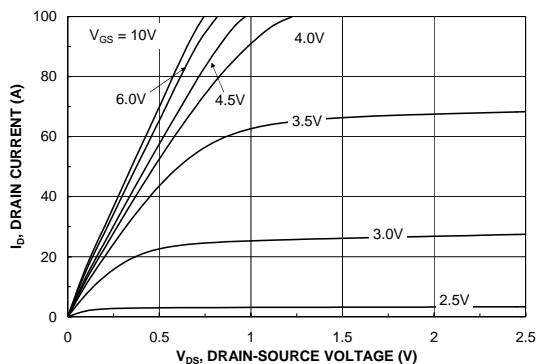


Figure 1. On-Region Characteristics.

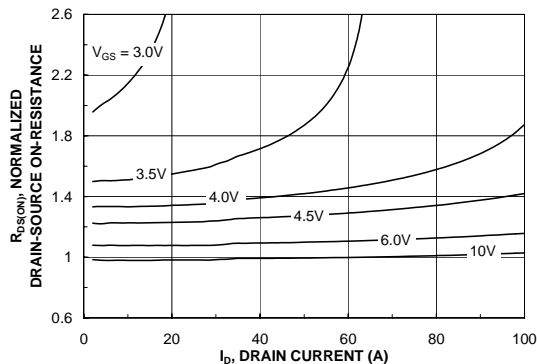


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

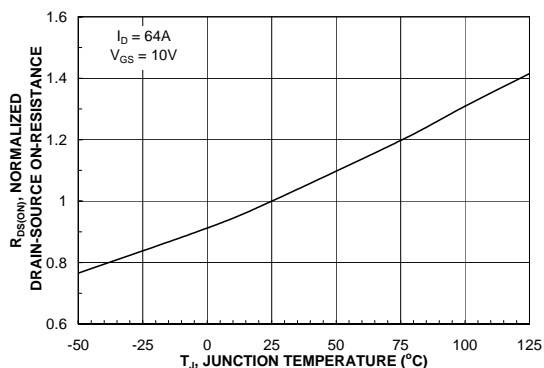


Figure 3. On-Resistance Variation with Temperature.

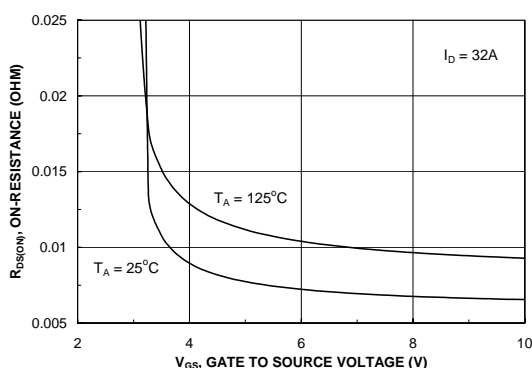


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

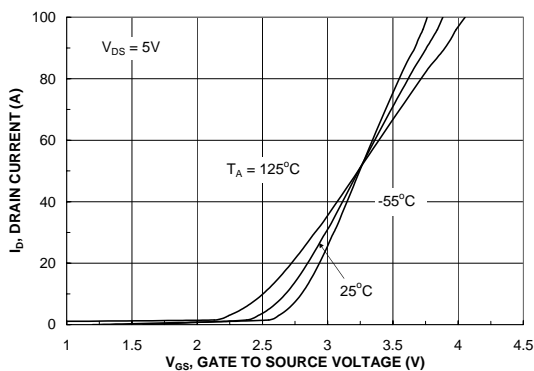


Figure 5. Transfer Characteristics.

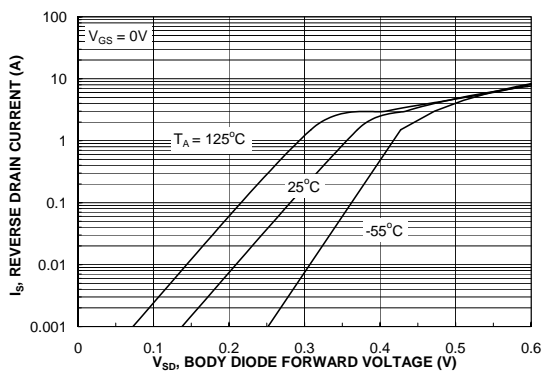


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)

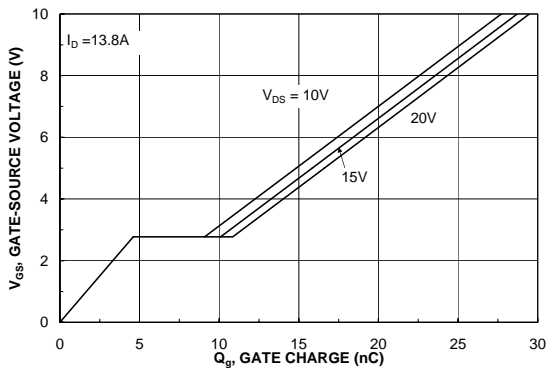


Figure 7. Gate Charge Characteristics.

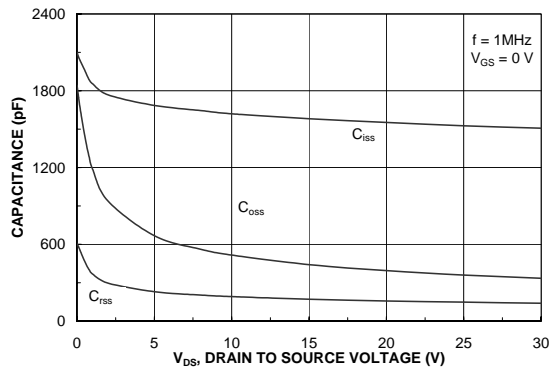


Figure 8. Capacitance Characteristics.

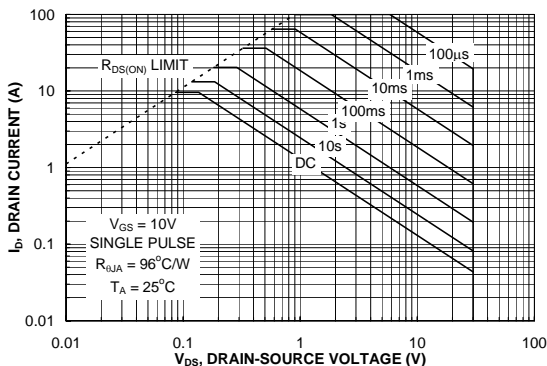


Figure 9. Maximum Safe Operating Area.

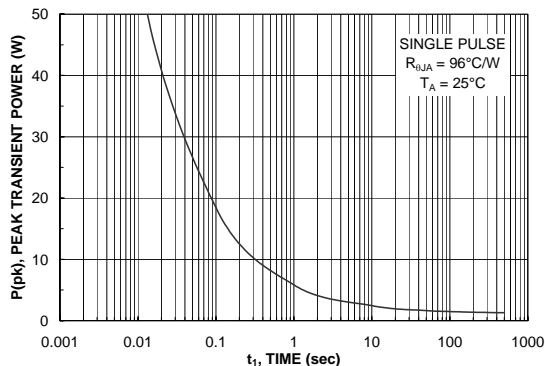


Figure 10. Single Pulse Maximum Power Dissipation.

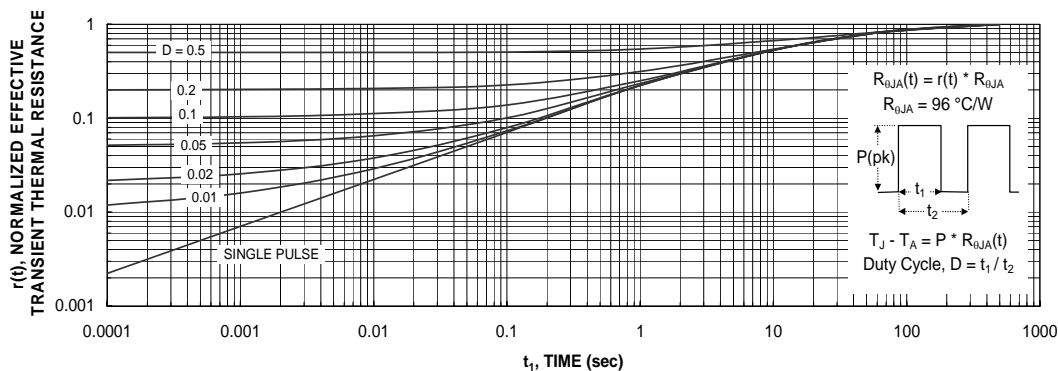


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

Typical Characteristics (continued)

SyncFET Schottky Body Diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 12 shows the reverse recovery characteristic of the FDD6670AS.

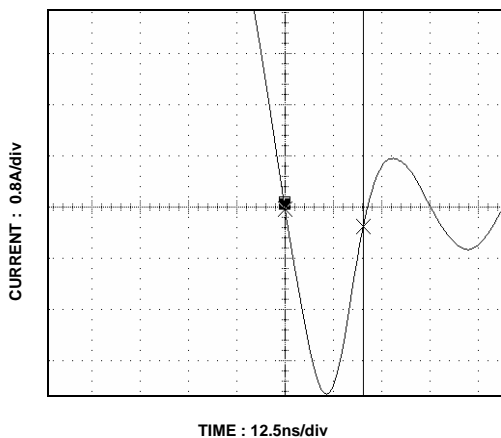


Figure 12. FDD6670AS SyncFET body diode reverse recovery characteristic.

For comparison purposes, Figure 13 shows the reverse recovery characteristics of the body diode of an equivalent size MOSFET produced without SyncFET (FDD6670A).

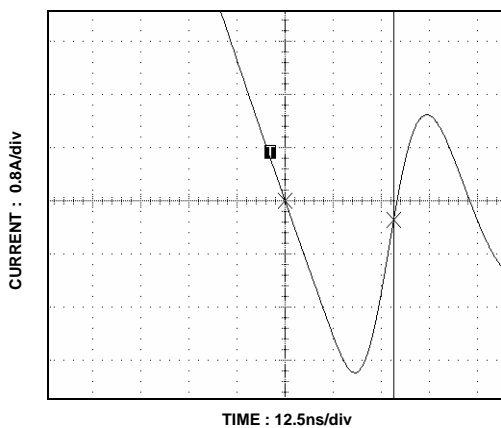


Figure 13. Non-SyncFET (FDD6670A) body diode reverse recovery characteristic.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

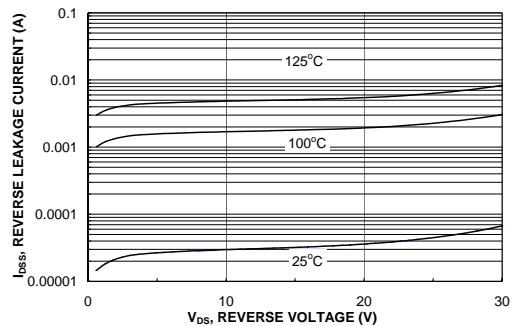


Figure 14. SyncFET body diode reverse leakage versus drain-source voltage and temperature.

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